



Title of Document:	Request for Change	Issue No. G22-02653	Rev. 0
Customer:		Issue date: 19 April 2022	
Title subject:	ZE connector Wafer: Addition of resin material	Revision date:	

Please take note that we would like to add one new manufacturer of PA 66 material for the wafer of ZE connector due to the supply restrictions by current resin manufacturer as follows.

1. Target product and Part number

Connector name		Part number
ZE connector Wafer	Top entry type	B**B-ZESK-D (T)(LF)(SN)(N) B**B-ZESK-1D (T)(LF)(SN)(N)

Note: Number of circuits in one or two-digit figures is indicated in *.

2. Details of the change

One new material manufacturer of resin material for the wafer of the aforementioned subject products shall be added to the current manufacturer.

At present, the additional products (made of additional resin) are only be available in natural color, and no colored variations are planned.

We are applying for overseas standard (UL standard) for additional products.

The part numbers associated with this addition are as follows.

	Material		Part No. <Example>
	Manufacturer	Part No.	
Current product	Asahi Kasei Chemicals Corp.	FG173	B**B-ZESK-D (T)(LF)(SN)(N)
Products after addition	Asahi Kasei Chemicals Corp.	FG173	B**B-ZESK-D (T)(LF)(SN)(N)
	BASF ENGINEERING PLASTICS CO., LTD.	A 30H1 V30	B**B-ZESK-D(SU) (T)(LF)(SN)(N)

3. Reason for the change

Because of difficulty of procuring the PA 66 material by current material manufacturer, this change shall be carried out.

Your thought understanding and consideration would be very much appreciated.

-End-



Prepared by: <i>K. Notsu</i>	Checked by: <i>T. Yamashita</i>	Reviewed by: <i>N. Tsuji</i>	Approved by: <i>K. Shiota</i>
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